



US 20240213066A1

(19) **United States**

(12) **Patent Application Publication**  
**Tschinderle et al.**

(10) **Pub. No.: US 2024/0213066 A1**

(43) **Pub. Date: Jun. 27, 2024**

(54) **FRAME SYSTEM FOR HOLDING A SUBSTRATE**

*H01L 21/677* (2006.01)

*H01L 21/687* (2006.01)

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(52) **U.S. Cl.**

CPC ..... *H01L 21/6734* (2013.01); *H01L 21/6715* (2013.01); *H01L 21/67379* (2013.01); *H01L 21/67736* (2013.01); *H01L 21/68728* (2013.01)

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(21) Appl. No.: **18/287,996**

(57)

**ABSTRACT**

(22) PCT Filed: **Feb. 16, 2022**

(86) PCT No.: **PCT/EP2022/053829**

§ 371 (c)(1),

(2) Date: **Oct. 23, 2023**

The present invention relates to a frame system. The frame system is configured for holding a substrate during a chemical and/or electrolytic surface treatment of the substrate. The frame system comprises a frame element and several finger units arranged at the frame element. The frame element is configured to at least partially surround lateral edges of the substrate and to spare at least a first surface or a second surface of the substrate to be accessible for the surface treatment. Each finger unit comprises a first finger and a second finger. The first finger is configured to contact the first surface of the substrate and the second finger is configured to contact the second surface of the substrate opposite to the first surface of the substrate. The first finger is movable relative to the frame element to clamp the substrate between the first finger and the second finger.

(30) **Foreign Application Priority Data**

Apr. 23, 2021 (EP) ..... 21170245.1

**Publication Classification**

(51) **Int. Cl.**

*H01L 21/673* (2006.01)

*H01L 21/67* (2006.01)

